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EFS ID: 60602
Application ID: 10763859
Title of Invention: SEMICONDUCTOR PACKAGE
HAVING REDUCED THICKNESS
First Named Inventor: TAE LEE
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Confirmation number: 8528
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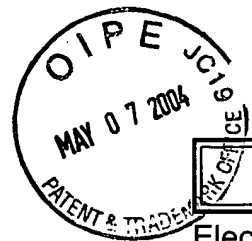
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Title of Invention	SEMICONDUCTOR PACKAGE HAVING REDUCED THICKNESS									
<p>Application Number: 10/763859 </p> <p>Date: 2004-01-23</p> <p>First Named Applicant: TAE HEON LEE</p> <p>Confirmation Number: 8528</p> <p>Attorney Docket Number: AMKOR053G</p>										
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Electronic Version v18

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<h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>5608265</td><td>1997-03-04</td><td>Kitano et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5608267</td><td>1997-03-04</td><td>Mahulikar et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5625222</td><td>1997-04-29</td><td>Yoneda et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>5633528</td><td>1997-05-27</td><td>Abbott et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>5639990</td><td>1997-06-17</td><td>Nishihara et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>5640047</td><td>1997-06-17</td><td>Nakashima</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>5641997</td><td>1997-06-24</td><td>Ohta et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>5643433</td><td>1997-07-01</td><td>Fukase et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>9</td><td>5644169</td><td>1997-07-01</td><td>Chun</td><td></td><td></td><td></td></tr></tbody></table>							init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	5608265	1997-03-04	Kitano et al.					2	5608267	1997-03-04	Mahulikar et al.					3	5625222	1997-04-29	Yoneda et al.					4	5633528	1997-05-27	Abbott et al.					5	5639990	1997-06-17	Nishihara et al.					6	5640047	1997-06-17	Nakashima					7	5641997	1997-06-24	Ohta et al.					8	5643433	1997-07-01	Fukase et al.					9	5644169	1997-07-01	Chun			
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Signature

Examiner Name	Date